積層造形用 金属粉末
Metal Powder for Additive Manufacturing

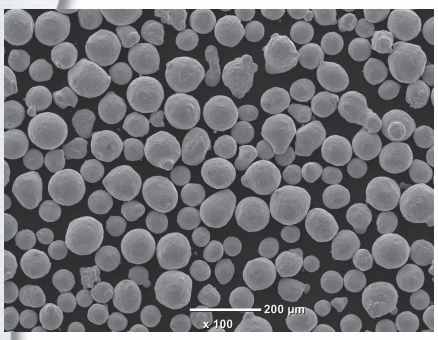
FAM Series 積層造形用 純銅及び銅合金粉末
Copper and Copper Alloy Powder for Additive Manufacturing

FAM-QCU 積層造形用純銅粉末
Pure copper powder for PBF and DED

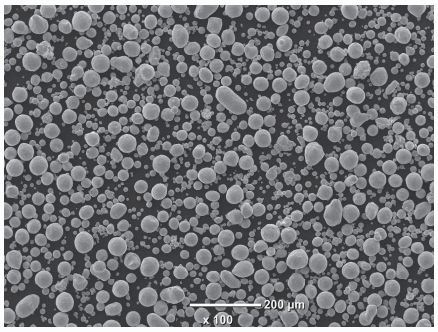
特長 *Advantages*

ガスアトマイズ法により製造した球状で、流動性のある純銅粉末。
高純度銅により導電部品や放熱部品への適用が可能。

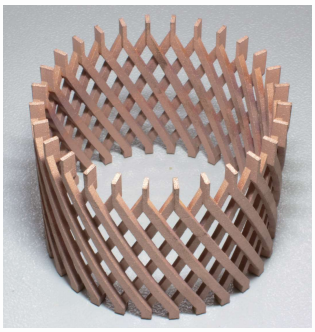
The spherically formed gas atomized pure copper powder has excellent fluidity for additive manufacturing.
High-purity copper makes it suitable for use in conductive parts and heat dissipation parts.



PBF-EB FAM-QCU 45-105 μm
(SEM image ×100)



PBF-LB FAM-QCU 10-45 μm
(SEM image ×100)



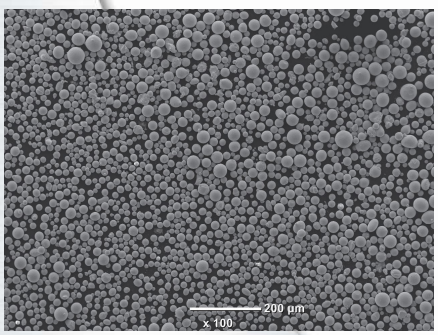
PBF-LB 造形例
Molding sample for PBF-LB

FAM-G101 積層造形用銅合金粉末
Copper alloy powder for PBF and DED

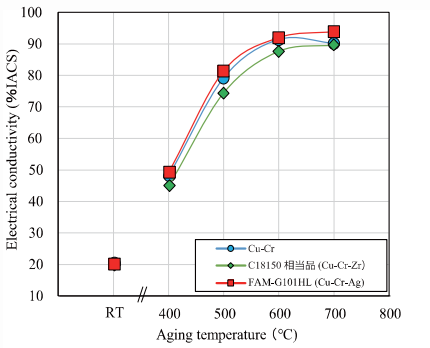
特長 *Advantages*

ガスアトマイズ法で作製した球状粉末で、波長1060nm近傍のLB熱源に対して高い造形性。
時効処理により高強度と高導電性を発現し、高強度・高導電部品への応用が可能。

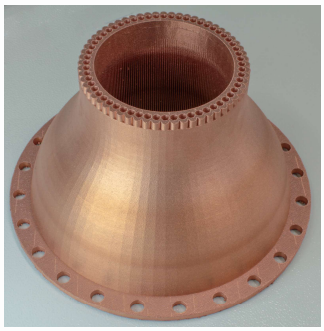
The copper alloy powder that is spherically formed by gas atomization method has high formability for LB heat sources with a wavelength of around 1060 nm.
Aging treatment enhances properties suitable for high strength and high electrical conductivity parts.



PBF-LB FAM-G101HL 10-45 μm
(SEM image ×100)



FAM-G101HL時効処理後の電気伝導性
Electrical conductivity after aging treatment



PBF-LB 造形例
Molding sample for PBF-LB

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FAM 製品紹介 HP